



REV.	ECN NO.	OR DESCRIPTION	REVISED	DATE
A	PDR NO. T130809-3A	Feng	2013.11.28	

- SPECIFICATIONS:**
- INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500 VDC MEGGER.
 - CONTACT RESISTANCE: 50mΩ MAX.
 - INSULATION VOLTAGE WITHSTAND: 500V AC FOR ONE MINUTE.
 - UNLESS OTHERWISE SPECIFIED, TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-85% IN HUMIDITY. BUT IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20°C±1°C IN TEMP.
 - LIFE TEST: 5,000 CYCLES.
 - INSERTION FORCE: 0.3 - 3.0Kg.
 - WITHDRAWAL FORCE: 0.3 - 3.0Kg.
 - AFTER HUMIDITY TEST, INSULATION RESISTANCE: 100MΩ MIN.
 - PACKAGING: TAPE & REEL.
 - TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
 - HALOGEN FREE PRODUCT IDENTIFICATION MARK ON JACK:
 - HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING:

I	MYLAR	1	0.075I	YELLOW
H	SHIELD	1	COPPER ALLOY 0.20T	WHITE Sn 80% ON SOLDER AREA ALL OVER IN 50u" Min
G	MAKE	1	COPPER ALLOY 0.20T	GOLD FLASH ON CONTACT AREA & SOLDER TAIL OVER IN 50u" MIN
F	TRANSFER TERMINAL	1	COPPER ALLOY 0.20T	GOLD FLASH ON CONTACT AREA
E	TIP	1	COPPER ALLOY 0.20T	WHITE Sn 120u" ON SOLDER AREA
D	RING-A	1	COPPER ALLOY 0.25T	ALL OVER IN 50u" Min
C	RING-B	1	COPPER ALLOY 0.20T	
B	EARTH	1	COPPER ALLOY 0.20T	
A	BODY	1	HIGH TEMP THERMOPLASTIC UL 94V-0	BLACK
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS: ANGLES:

X :±0.5 X :±2°
X.X :±0.3 X.X :±1°
X.XX :±0.2

Singatron Enterprise Co., Ltd.
信晉企業股份有限公司

TITLE: 3.5Ø PHONE JACK

DWN Feng PART NO. 2S1J3052-015111F
CHKD BRUCE SCALE 1:1 UNIT: mm
APVD LUSSEN SIZE: A3 SHEET: 10F1 REV: A

CUSTOMER COPY

1 2 3 4 5 6 7 8

A B C D E F

1 2 3 4 5 6 7 8

A B C D E F

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